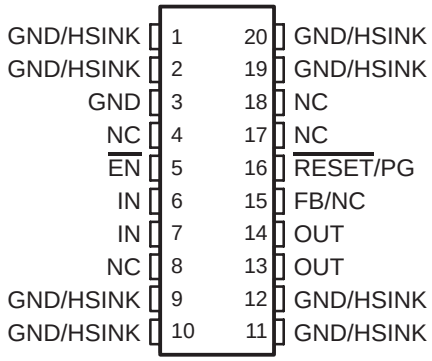
TPS77501-Q1, ’515-Q1, ’516-Q1, ’518-Q1, ’525-Q1, ’533-Q1 WITH $\overline{\text{RESET}}$ OUTPUT
TPS77601-Q1, ’77615-Q1, ’77618-Q1, ’77625-Q1, ’77628-Q1, ’77633-Q1 WITH PG OUTPUT
FAST-TRANSIENT-RESPONSE 500-mA LOW-DROPOUT VOLTAGE REGULATORS

SGLS012B − MARCH 2003 − REVISED APRIL 2008

- **Qualified for Automotive Applications**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Open Drain Power-On Reset With 200-ms Delay (TPS775xx)**
- **Open Drain Power Good (TPS776xx)**
- **500-mA Low-Dropout Voltage Regulator**
- **Available in 1.5-V, 1.6-V (TPS77516 Only), 1.8-V, 2.5-V, 2.8-V (TPS77628 Only), 3.3-V Fixed Output and Adjustable Versions**
- **Dropout Voltage to 169 mV (Typ) at 500 mA (TPS77x33)**
- **Ultralow 85 μA Typical Quiescent Current**
- **Fast Transient Response**
- **2% Tolerance Over Specified Conditions for Fixed-Output Versions**
- **20-Pin TSSOP PowerPAD™ (PWP) Package**
- **Thermal Shutdown Protection**

PWP PACKAGE
(TOP VIEW)



NC − No internal connection

description

The TPS775xx and TPS776xx devices are designed to have a fast transient response and be stable with a 10-μF low ESR capacitors. This combination provides high performance at a reasonable cost.

Because the PMOS device behaves as a low-value resistor, the dropout voltage is very low (typically 169 mV at an output current of 500 mA for the TPS77x33) and is directly proportional to the output current. Additionally, since the PMOS pass element is a voltage-driven device, the quiescent current is very low and independent of output loading (typically 85 μA over the full range of output current, 0 mA to 500 mA). These two key specifications yield a significant improvement in operating life for battery-powered systems. This LDO family also features a sleep mode; applying a TTL high signal to $\overline{\text{EN}}$ (enable) shuts down the regulator, reducing the quiescent current to 1 μA at T_J = 25°C.

The $\overline{\text{RESET}}$ output of the TPS775xx initiates a reset in microcomputer and microprocessor systems in the event of an undervoltage condition. An internal comparator in the TPS775xx monitors the output voltage of the regulator to detect an undervoltage condition on the regulated output voltage.

Power good (PG) of the TPS776xx is an active high output, which can be used to implement a power-on reset or a low-battery indicator.

The TPS775xx and TPS776xx are offered in 1.5-V, 1.6-V (TPS77516 only), 1.8-V, 2.5-V, 2.8 V (TPS77628 only), and 3.3-V fixed-voltage versions and in an adjustable version (programmable over the range of 1.5 V to 5.5 V for TPS77501 option and 1.2 V to 5.5 V for TPS77601 option). Output voltage tolerance is specified as a maximum of 2% over line, load, and temperature ranges. The TPS775xx and TPS776xx families are available in 20 pin TSSOP package.

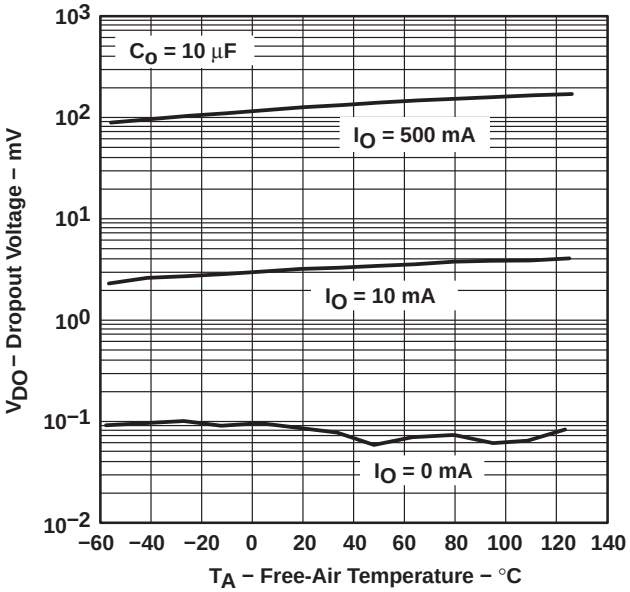
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PowerPAD is a trademark of Texas Instruments.

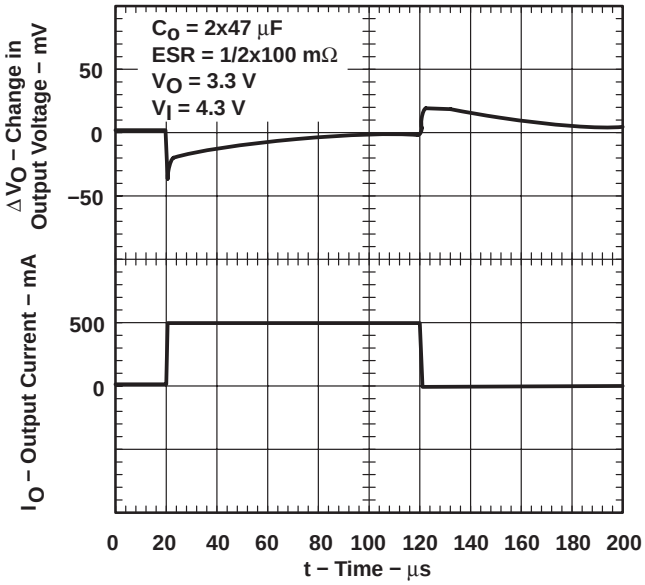
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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TPS77x33
DROPOUT VOLTAGE
vs
FREE-AIR TEMPERATURE



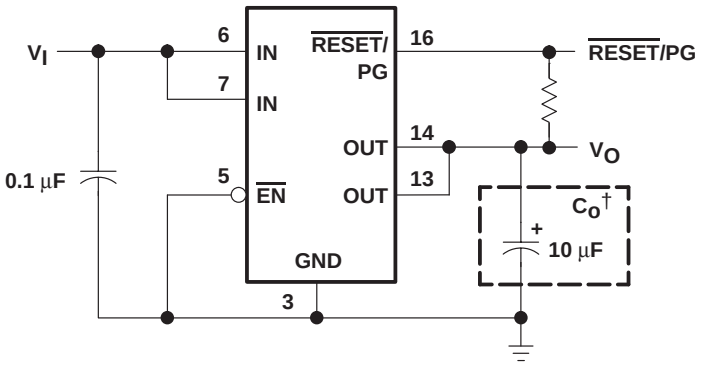
TPS77x33
LOAD TRANSIENT RESPONSE



AVAILABLE OPTIONS†

T_J	OUTPUT VOLTAGE (V)	PACKAGED DEVICES	
	TYP	TSSOP (PWP)	
−40°C to 125°C	3.3	TPS77533PWPQ1	TPS77633PWPQ1
	2.5	TPS77525PWPQ1	TPS77625PWPQ1
	2.8	—	TPS77628PWPQ1
	1.8	TPS77518PWPQ1	TPS77618PWPQ1
	1.6	TPS77516PWPQ1§	—
	1.5	TPS77515PWPQ1	TPS77615PWPQ1
	Adjustable‡ 1.2 V to 5.5 V	—	TPS77601PWPQ1
	Adjustable‡ 1.5 V to 5.5 V	TPS77501PWPQ1	—

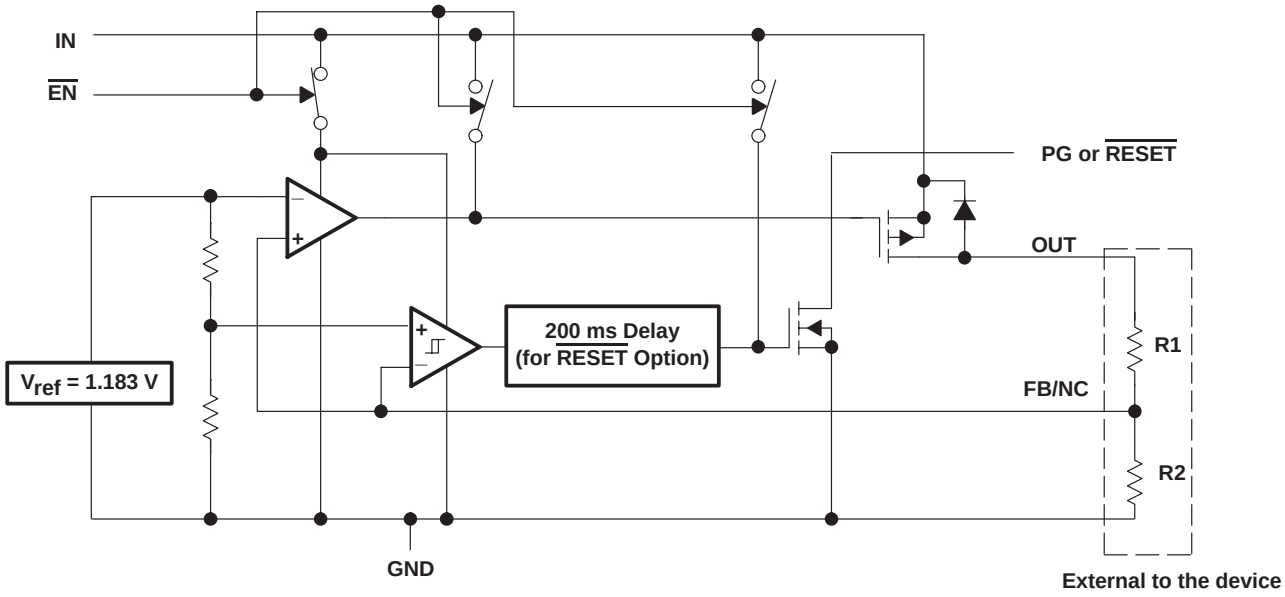
† The TPS775xx has an open-drain power-on reset with a 200-ms delay function. The TPS776xx has an open-drain power good function.
‡ The TPS77x01 is programmable using an external resistor divider (see application information). The PWP package is available taped and reeled. Add an R suffix to the device type (e.g., TPS77501QPWPRQ1).
§ TPS77516 is Product Preview.



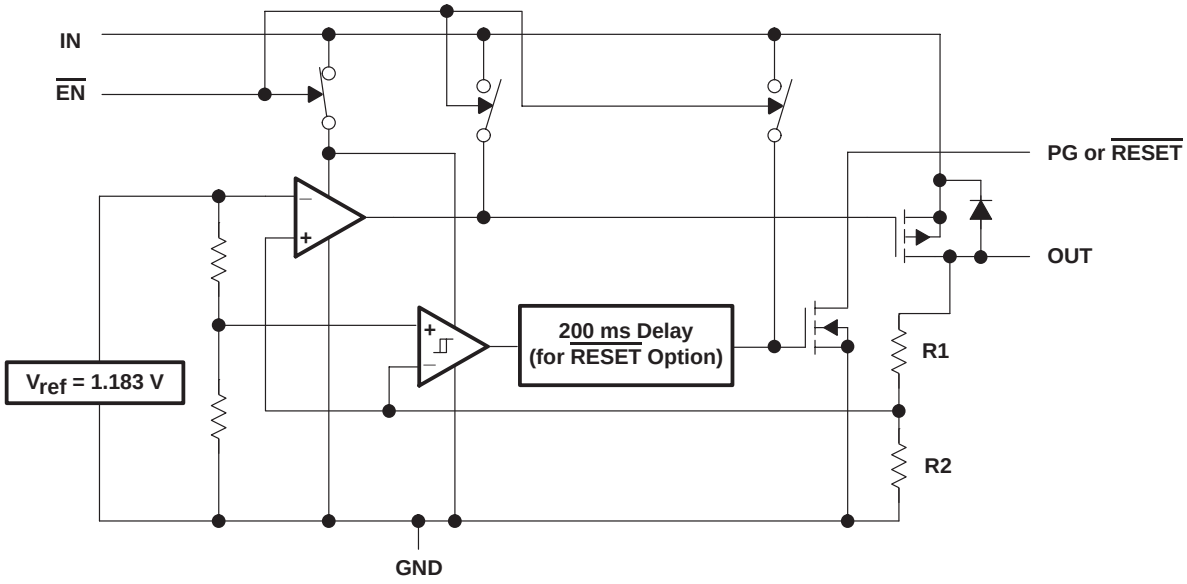
† See application information section for capacitor selection details.

Figure 1. Typical Application Configuration for Fixed Output Options

functional block diagram—adjustable version



functional block diagram—fixed-voltage version



Terminal Functions

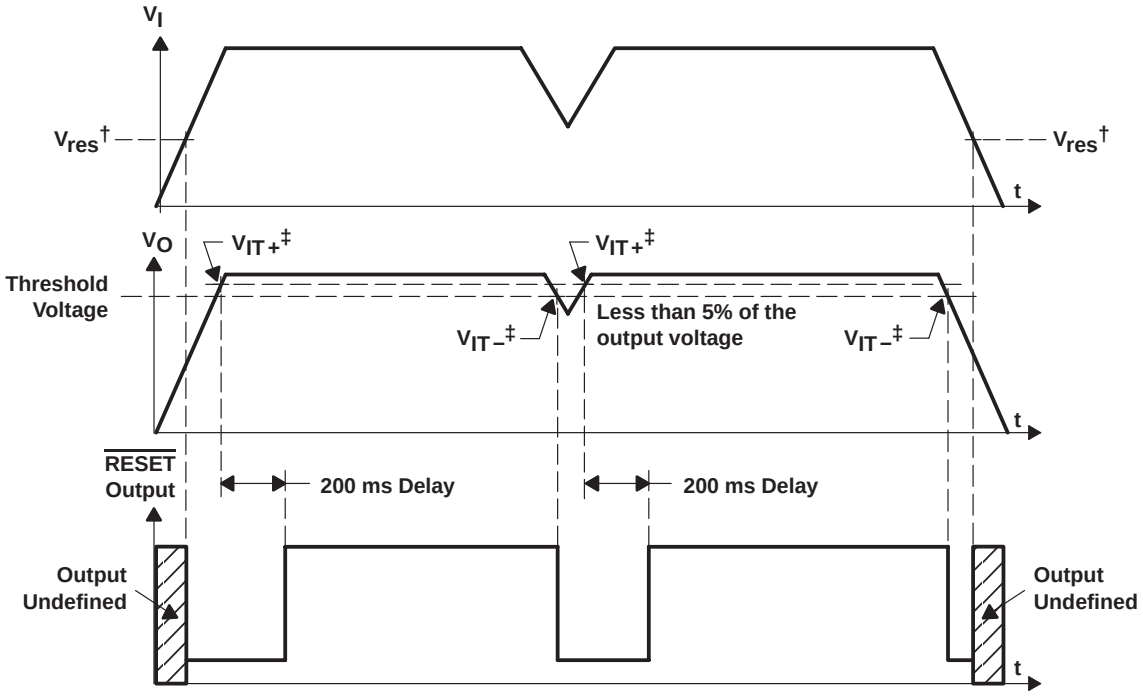
TSSOP Package (TPS775xx)

TERMINAL NAME	TERMINAL NO.	I/O	DESCRIPTION
$\overline{\text{EN}}$	5	I	Enable input
FB/NC	15	I	Feedback input voltage for adjustable device (no connect for fixed options)
GND	3		Regulator ground
GND/HSINK	1, 2, 9, 10, 11, 12, 19, 20		Ground/heatsink
IN	6, 7	I	Input voltage
NC	4, 8, 17, 18		No connect
OUT	13, 14	O	Regulated output voltage
$\overline{\text{RESET}}$	16	O	$\overline{\text{RESET}}$ output

TSSOP Package (TPS776xx)

TERMINAL NAME	TERMINAL NO.	I/O	DESCRIPTION
$\overline{\text{EN}}$	5	I	Enable input
FB/NC	15	I	Feedback input voltage for adjustable device (no connect for fixed options)
GND	3		Regulator ground
GND/HSINK	1, 2, 9, 10, 11, 12, 19, 20		Ground/heatsink
IN	6, 7	I	Input voltage
NC	4, 8, 17, 18		No connect
OUT	13, 14	O	Regulated output voltage
PG	16	O	PG output

TPS775xx $\overline{\text{RESET}}$ timing diagram



† V_{res} is the minimum input voltage for a valid $\overline{\text{RESET}}$. The symbol V_{res} is not currently listed within EIA or JEDEC standards for semiconductor symbology.

‡ V_{IT} −Trip voltage is typically 5% lower than the output voltage (95%V_O) V_{IT-} to V_{IT+} is the hysteresis voltage.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Input voltage range‡, V_I . . . . . −0.3 V to 13.5 V
Voltage range at $\overline{\text{EN}}$ . . . . . −0.3 V to 16.5 V
Maximum $\overline{\text{RESET}}$ voltage (TPS775xx) . . . . . 16.5 V
Maximum PG voltage (TPS776xx) . . . . . 16.5 V
Peak output current . . . . . Internally limited
Output voltage, V_O (OUT, FB) . . . . . 7 V
Continuous total power dissipation . . . . . See dissipation rating tables
Operating virtual junction temperature range, T_J . . . . . −40°C to 125°C
Storage temperature range, T_{stg} . . . . . −65°C to 150°C
ESD rating, HBM . . . . . 2 kV

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
‡ All voltage values are with respect to network terminal ground.

DISSIPATION RATING TABLE − FREE-AIR TEMPERATURES

PACKAGE	AIR FLOW (CFM)	T_A < 25°C POWER RATING	DERATING FACTOR ABOVE T_A = 25°C	T_A = 70°C POWER RATING	T_A = 85°C POWER RATING
PWP§	0	2.9 W	23.5 mW/°C	1.9 W	1.5 W
	300	4.3 W	34.6 mW/°C	2.8 W	2.2 W
PWP¶	0	3 W	23.8 mW/°C	1.9 W	1.5 W
	300	7.2 W	57.9 mW/°C	4.6 W	3.8 W

§ This parameter is measured with the recommended copper heat sink pattern on a 1-layer PCB, 5-in × 5-in PCB, 1 oz. copper, 2-in × 2-in coverage (4 in^2).
¶ This parameter is measured with the recommended copper heat sink pattern on a 8-layer PCB, 1.5-in × 2-in PCB, 1 oz. copper with layers 1, 2, 4, 5, 7, and 8 at 5% coverage (0.9 in^2) and layers 3 and 6 at 100% coverage (6 in^2). For more information, refer to TI technical brief SLMA002.

recommended operating conditions

		MIN	MAX	UNIT
Input voltage, V_I#		2.7	10	V
Output voltage range, V_O	TPS77501	1.5	5.5	V
	TPS77601	1.2	5.5	
Output current, I_O (see Note 1)		0	500	mA
Operating virtual junction temperature, T_J (see Note 1)		−40	125	°C

To calculate the minimum input voltage for your maximum output current, use the following equation: $V_{I(min)} = V_{O(max)} + V_{DO(max\ load)}$.
NOTE 1: Continuous current and operating junction temperature are limited by internal protection circuitry, but it is not recommended that the device operate under conditions beyond those specified in this table for extended periods of time.

electrical characteristics over recommended operating free-air temperature range, $V_I = V_{O(typ)} + 1$ V, $I_O = 1$ mA, $\overline{EN} = 0$ V, $C_o = 10$ µF (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
Output voltage (10 µA to 500 mA load) (see Note 2)	TPS77501	$1.5\text{ V} \le V_O \le 5.5\text{ V}$, $T_J = 25°C$		V_O		V
		$1.5\text{ V} \le V_O \le 5.5\text{ V}$, $T_J = -40°C$ to $125°C$	$0.98V_O$		$1.02V_O$	
	TPS77601	$1.2\text{ V} \le V_O \le 5.5\text{ V}$, $T_J = 25°C$		V_O		
		$1.2\text{ V} \le V_O \le 5.5\text{ V}$, $T_J = -40°C$ to $125°C$	$0.98V_O$		$1.02V_O$	
	TPS77x15	$T_J = 25°C$, $2.7\text{ V} < V_{IN} < 10\text{ V}$		1.5		
		$T_J = -40°C$ to $125°C$, $2.7\text{ V} < V_{IN} < 10\text{ V}$	1.470		1.530	
	TPS77516	$T_J = 25°C$, $2.7\text{ V} < V_{IN} < 10\text{ V}$		1.6		V
		$T_J = -40°C$ to $125°C$, $2.7\text{ V} < V_{IN} < 10\text{ V}$	1.568		1.632	
	TPS77x18	$T_J = 25°C$, $2.8\text{ V} < V_{IN} < 10\text{ V}$		1.8		
		$T_J = -40°C$ to $125°C$, $2.8\text{ V} < V_{IN} < 10\text{ V}$	1.764		1.836	
	TPS77x25	$T_J = 25°C$, $3.5\text{ V} < V_{IN} < 10\text{ V}$		2.5		
		$T_J = -40°C$ to $125°C$, $3.5\text{ V} < V_{IN} < 10\text{ V}$	2.450		2.550	
	TPS77628	$T_J = 25°C$, $3.8\text{ V} < V_{IN} < 10\text{ V}$		2.8		V
		$T_J = -40°C$ to $125°C$, $3.8\text{ V} < V_{IN} < 10\text{ V}$	2.744		2.856	
	TPS77x33	$T_J = 25°C$, $4.3\text{ V} < V_{IN} < 10\text{ V}$		3.3		
		$T_J = -40°C$ to $125°C$, $4.3\text{ V} < V_{IN} < 10\text{ V}$	3.234		3.366	
Quiescent current (GND current) $\overline{EN} = 0$V, (see Note 2)		$10\text{ µA} < I_O < 500\text{ mA}$, $T_J = 25°C$		85		µA
		$I_O = 500$ mA, $T_J = -40°C$ to $125°C$			125	
Output voltage line regulation ($\Delta V_O/V_O$) (see Notes 2 and 3)		$V_O + 1\text{ V} < V_I \le 10\text{ V}$, $T_J = 25°C$		0.01		%/V
Load regulation				3		mV
Output noise voltage (TPS77x18)		BW = 200 Hz to 100 kHz, $I_C = 500$ mA, $C_O = 10$ µF, $T_J = 25°C$		53		µVrms
Output current limit		$V_O = 0$ V		1.7	2	A
Thermal shutdown junction temperature				150		°C
Standby current		$\overline{EN} = V_I$, $T_J = 25°C$, $2.7\text{ V} < V_I < 10\text{ V}$		1		µA
		$\overline{EN} = V_I$, $T_J = -40°C$ to $125°C$, $2.7\text{ V} < V_I < 10\text{ V}$			10	µA
FB input current	TPS77x01	FB = 1.5 V		2		nA
High level enable input voltage			1.7			V
Low level enable input voltage					0.9	V
Power supply ripple rejection (see Note 2)		f = 1 KHz, $C_o = 10$ µF, $T_J = 25°C$		60		dB

NOTES: 2. Minimum IN operating voltage is 2.7 V or $V_{O(typ)} + 1$ V, whichever is greater. Maximum IN voltage 10V.

3. If $V_O \le 1.8$ V then $V_{Imin} = 2.7$ V, $V_{Imax} = 10$ V:

$$\text{Line Reg. (mV)} = (\%/V) \times \frac{V_O\left(V_{Imax} - 2.7\text{ V}\right)}{100} \times 1000$$

If $V_O \ge 2.5$ V then $V_{Imin} = V_O + 1$ V, $V_{Imax} = 10$ V:

$$\text{Line Reg. (mV)} = (\%/V) \times \frac{V_O\left(V_{Imax} - \left(V_O + 1\text{ V}\right)\right)}{100} \times 1000$$

electrical characteristics over recommended operating free-air temperature range, $V_I = V_{O(typ)} + 1$ V, $I_O = 1$ mA, $\overline{EN} = 0$ V, $C_o = 10$ μF (unless otherwise noted) (continued)

PARAMETER			TEST CONDITIONS		MIN	TYP	MAX	UNIT
Reset (TPS775xx)	Minimum input voltage for valid $\overline{\text{RESET}}$		$I_{O(RESET)}$ = 300 μA			1.1		V
	Trip threshold voltage		V_O decreasing		92		98	$\%V_O$
	Hysteresis voltage		Measured at V_O			0.5		$\%V_O$
	Output low voltage		V_I = 2.7 V,	$I_{O(RESET)}$ = 1mA		0.15	0.4	V
	Leakage current		$V_{(RESET)}$ = 5 V				1	μA
	RESET time-out delay					200		ms
PG (TPS776xx)	Minimum input voltage for valid PG		$I_{O(PG)}$ = 300 μA			1.1		V
	Trip threshold voltage		V_O decreasing		92		98	$\%V_O$
	Hysteresis voltage		Measured at V_O			0.5		$\%V_O$
	Output low voltage		V_I = 2.7 V,	$I_{O(PG)}$ = 1 mA		0.15	0.4	V
	Leakage current		$V_{(PG)}$ = 5 V				1	μA
Input current ($\overline{EN}$)			$\overline{EN}$ = 0 V		−1	0	1	μA
			$\overline{EN}$ = V_I		−1		1	
Dropout voltage (see Note 4)		TPS77628	I_O = 500 mA,	T_J = 25°C		285		mV
			I_O = 500 mA,	T_J = −40°C to 125°C			410	
		TPS77533	I_O = 500 mA,	T_J = 25°C		169		
			I_O = 500 mA,	T_J = −40°C to 125°C			287	
		TPS77633	I_O = 500 mA,	T_J = 25°C		169		
			I_O = 500 mA,	T_J = −40°C to 125°C			287	

NOTE 4: IN voltage equals V_O(typ) − 100 mV; TPS77x15, TPS77516, TPS77x18, and TPS77x25 dropout voltage limited by input voltage range limitations (i.e., TPS77x33 input voltage needs to drop to 3.2 V for purpose of this test).

TYPICAL CHARACTERISTICS

Table of Graphs

			FIGURE
V_O	Output voltage	vs Output current	2, 3, 4
		vs Free-air temperature	5, 6, 7
	Ground current	vs Free-air temperature	8
	Power supply ripple rejection	vs Frequency	9
	Output spectral noise density	vs Frequency	10
Z_0	Output impedance	vs Frequency	11
V_{DO}	Dropout voltage	vs Input voltage	12
		vs Free-air temperature	13
	Input voltage (min)	vs Output voltage	14
	Line transient response		15, 17
	Load transient response		16, 18
V_O	Output voltage	vs Time	19
	Equivalent series resistance (ESR)	vs Output current	21 − 24

TYPICAL CHARACTERISTICS

TPS77x33
OUTPUT VOLTAGE
vs
OUTPUT CURRENT

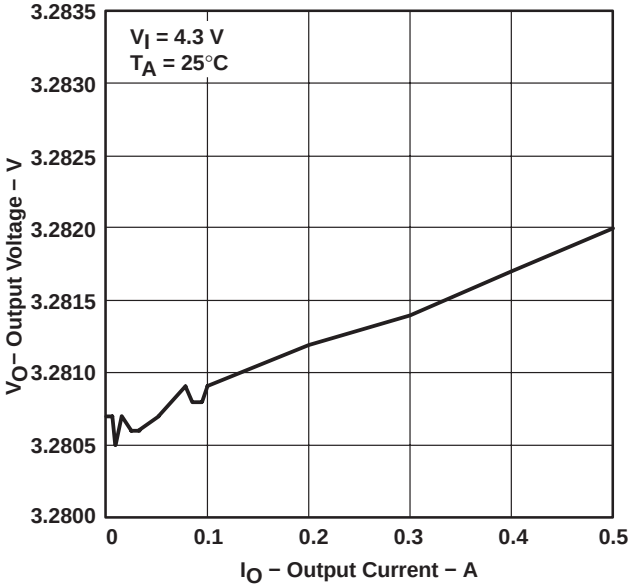


Figure 2

TPS77x15
OUTPUT VOLTAGE
vs
OUTPUT CURRENT

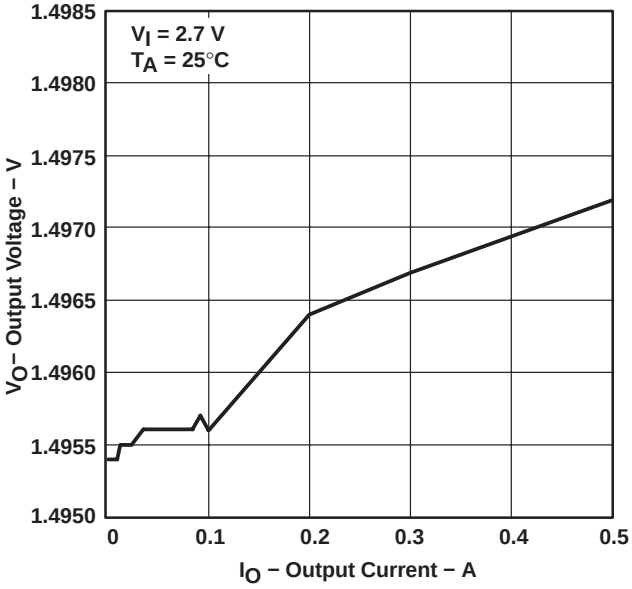


Figure 3

TPS77x25
OUTPUT VOLTAGE
vs
OUTPUT CURRENT

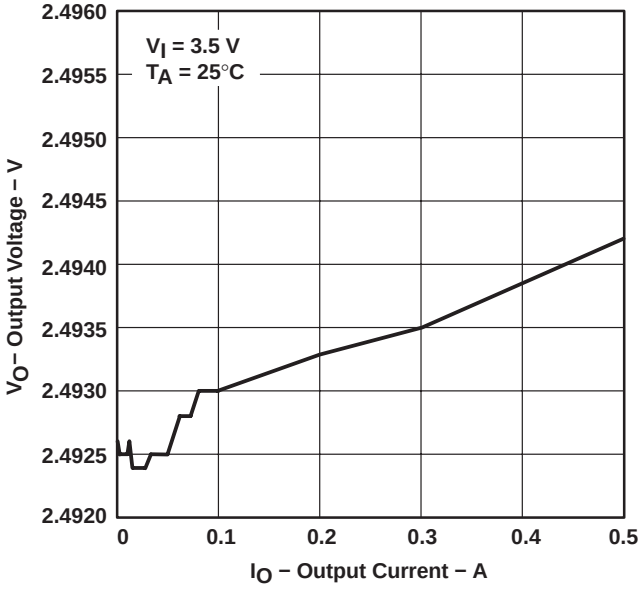


Figure 4

TPS77x33
OUTPUT VOLTAGE
vs
FREE-AIR TEMPERATURE

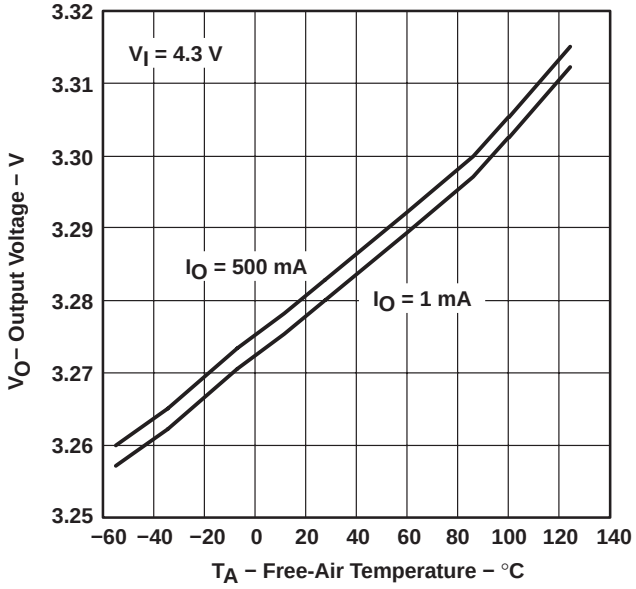


Figure 5

TYPICAL CHARACTERISTICS

TPS77x15
OUTPUT VOLTAGE
vs
FREE-AIR TEMPERATURE

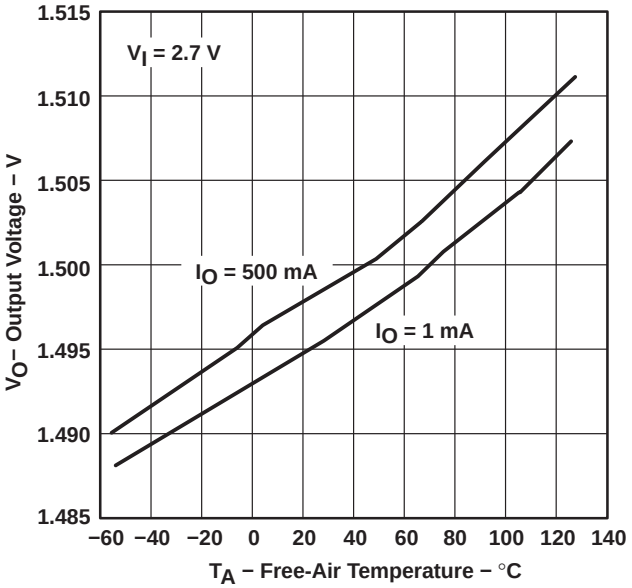


Figure 6

TPS77x25
OUTPUT VOLTAGE
vs
FREE-AIR TEMPERATURE

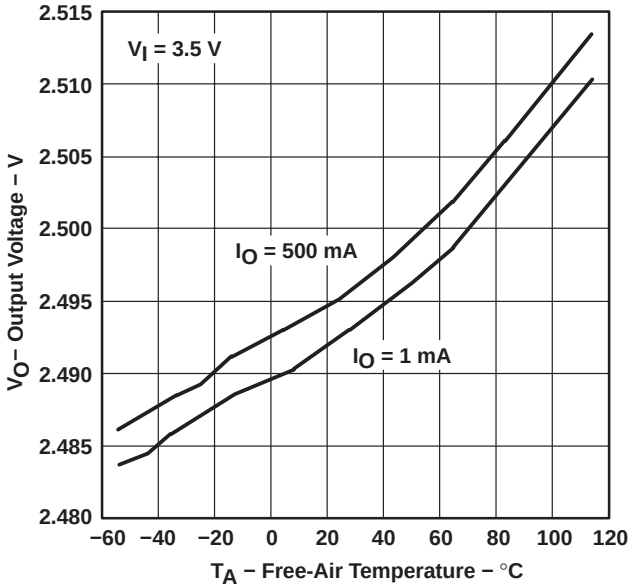


Figure 7

TPS77xxx
GROUND CURRENT
vs
FREE-AIR TEMPERATURE

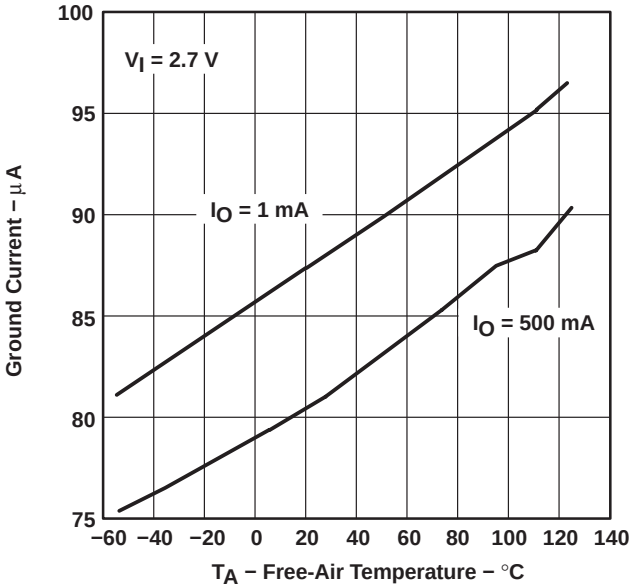


Figure 8

TPS77x33
POWER SUPPLY RIPPLE REJECTION
vs
FREQUENCY

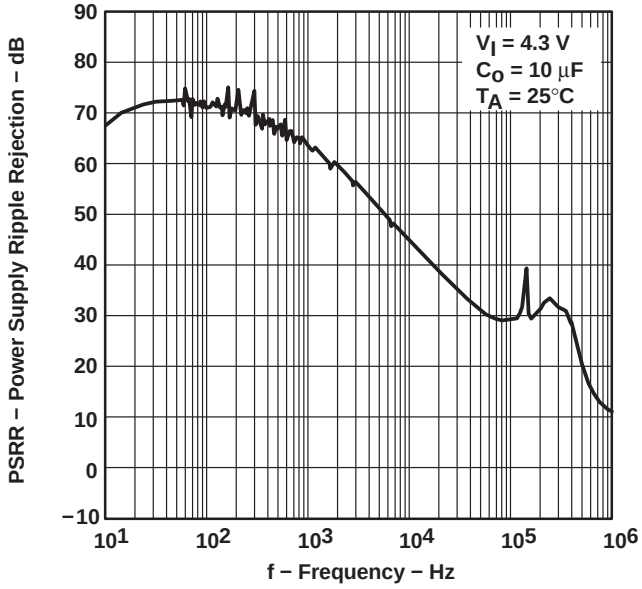


Figure 9

TYPICAL CHARACTERISTICS

TPS77x33
OUTPUT SPECTRAL NOISE DENSITY
vs
FREQUENCY

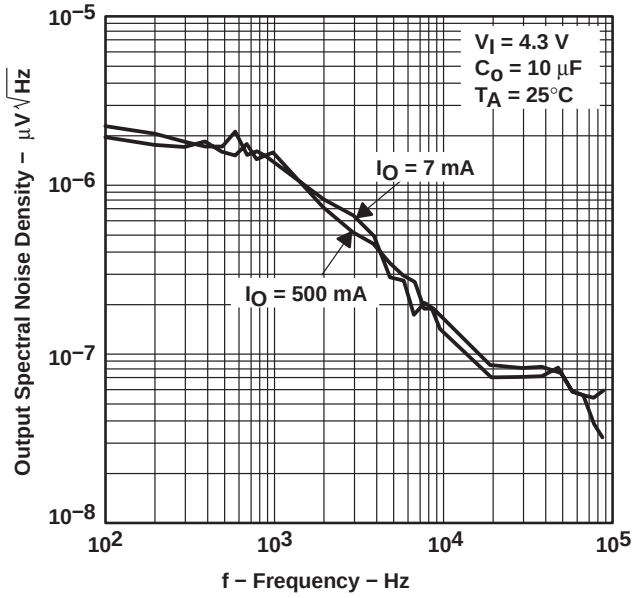


Figure 10

TPS77x33
OUTPUT IMPEDANCE
vs
FREQUENCY

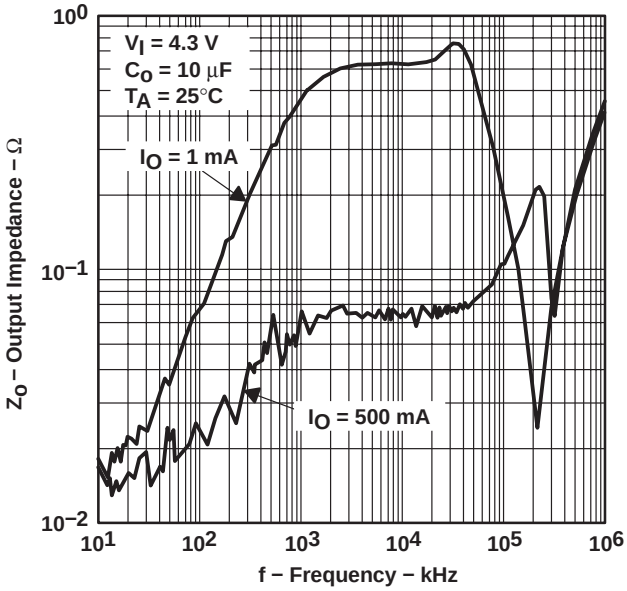


Figure 11

TPS77x01
DROPOUT VOLTAGE
vs
INPUT VOLTAGE

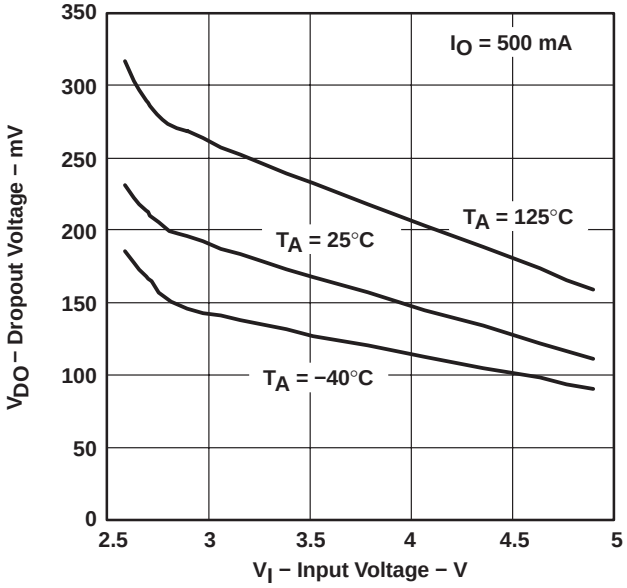


Figure 12

TPS77x33
DROPOUT VOLTAGE
vs
FREE-AIR TEMPERATURE

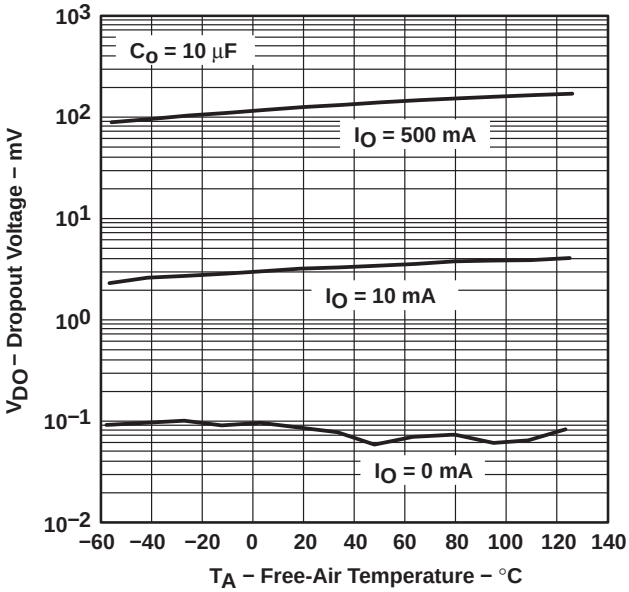


Figure 13

TYPICAL CHARACTERISTICS

**INPUT VOLTAGE (MIN)
vs
OUTPUT VOLTAGE**

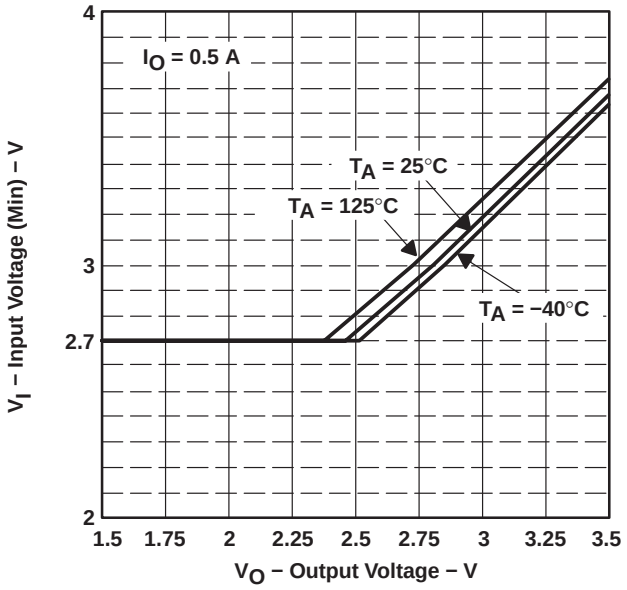


Figure 14

**TPS77x15
LINE TRANSIENT RESPONSE**

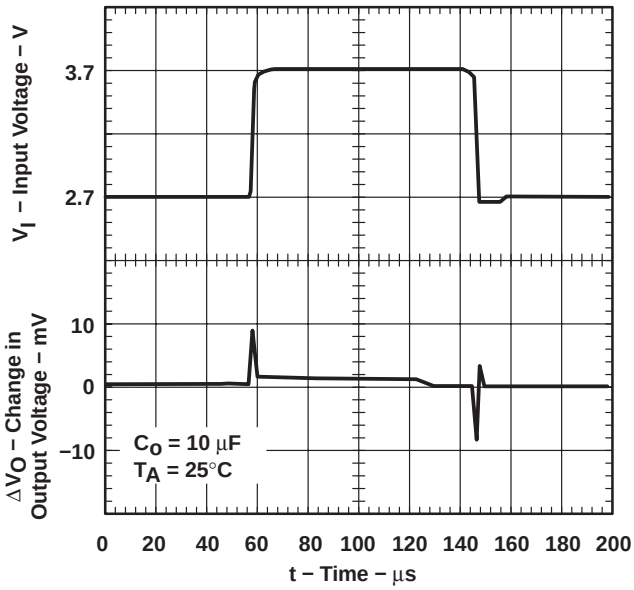


Figure 15

**TPS77x15
LOAD TRANSIENT RESPONSE**

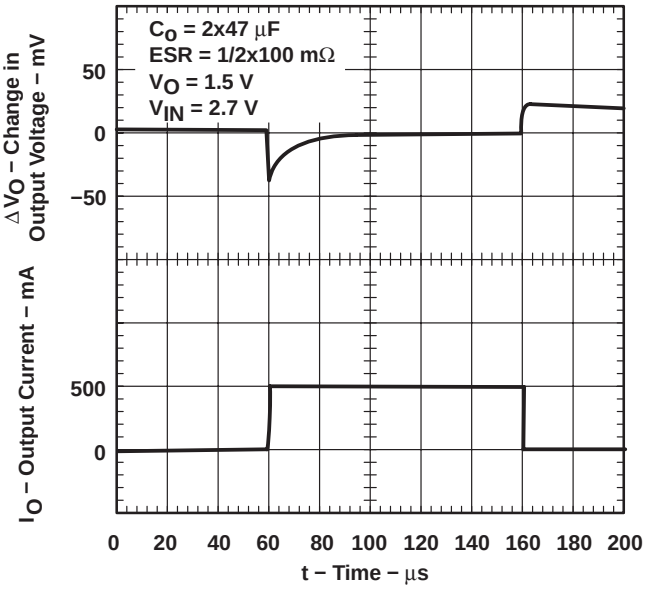


Figure 16

**TPS77x33
LINE TRANSIENT RESPONSE**

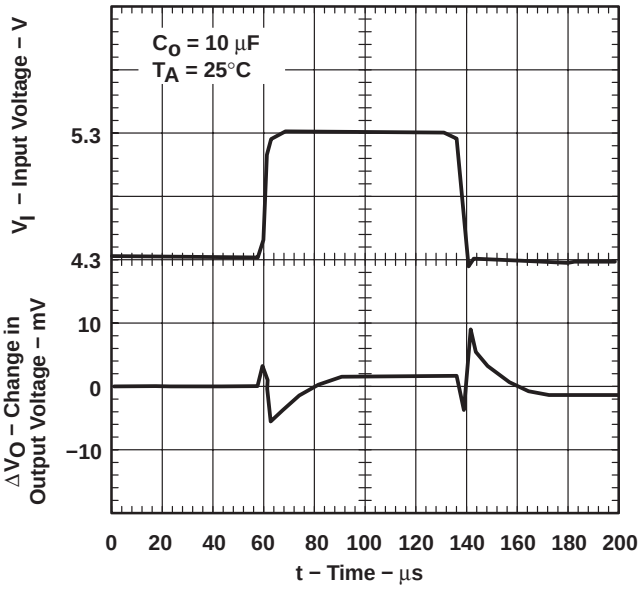


Figure 17

TYPICAL CHARACTERISTICS

TPS77x33
LOAD TRANSIENT RESPONSE

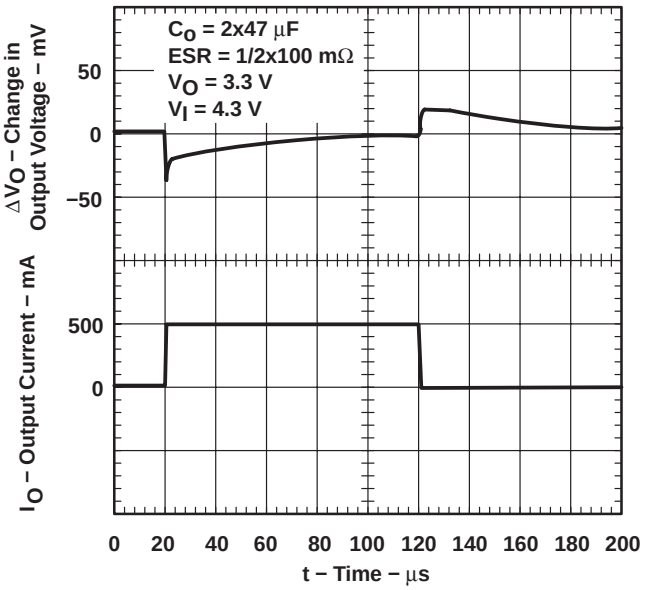


Figure 18

TPS77x33
OUTPUT VOLTAGE
vs
TIME (AT STARTUP)

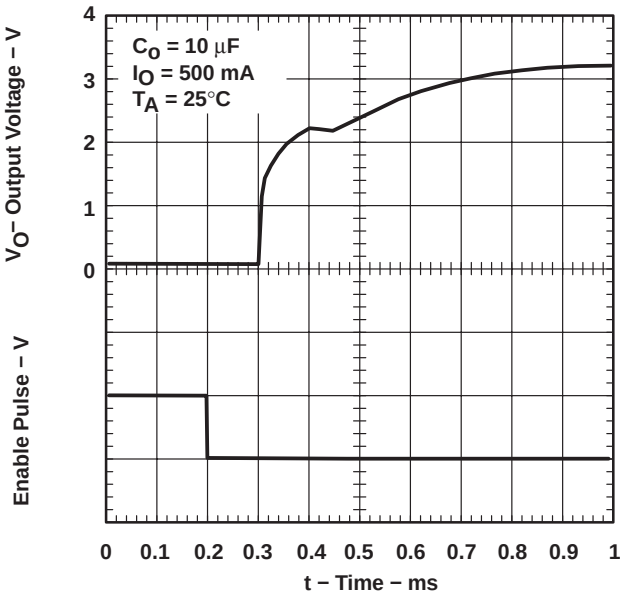


Figure 19

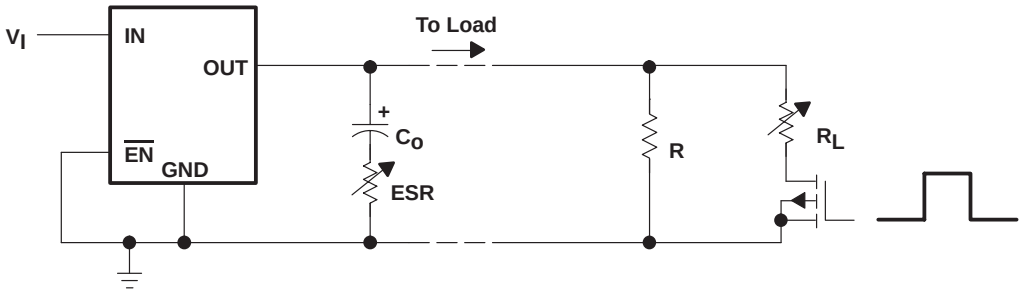


Figure 20. Test Circuit for Typical Regions of Stability (Figures 21 through 24) (Fixed Output Options)

TYPICAL CHARACTERISTICS

TYPICAL REGION OF STABILITY
EQUIVALENT SERIES RESISTANCE† vs OUTPUT CURRENT

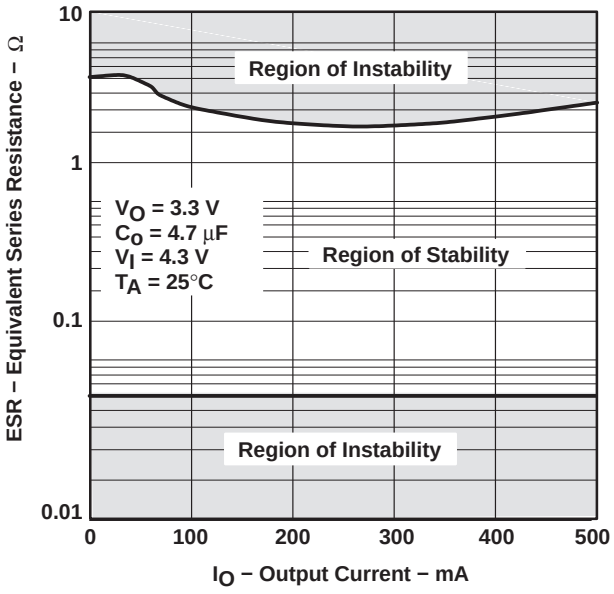


Figure 21

TYPICAL REGION OF STABILITY
EQUIVALENT SERIES RESISTANCE† vs OUTPUT CURRENT

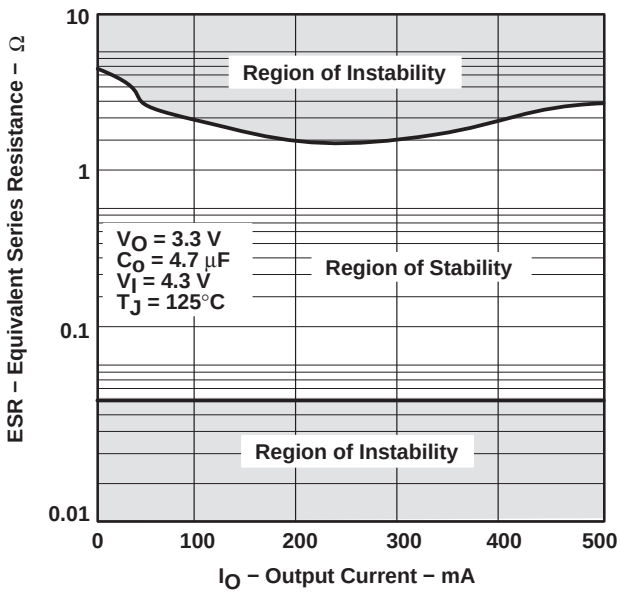


Figure 22

TYPICAL REGION OF STABILITY
EQUIVALENT SERIES RESISTANCE† vs OUTPUT CURRENT

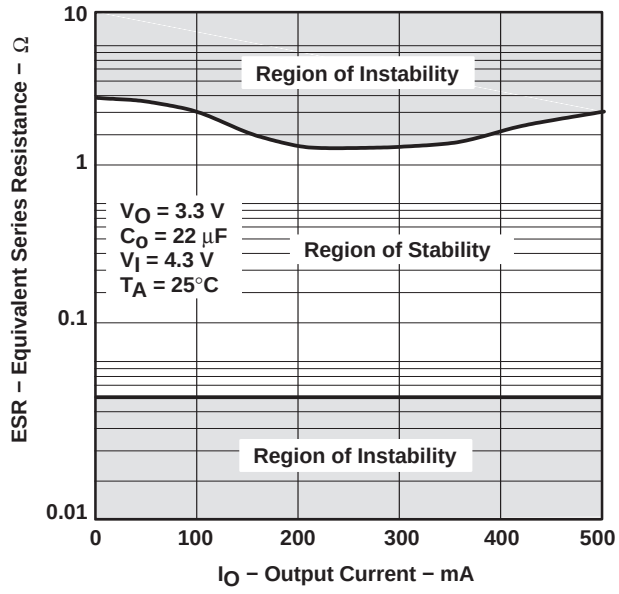


Figure 23

TYPICAL REGION OF STABILITY
EQUIVALENT SERIES RESISTANCE† vs OUTPUT CURRENT

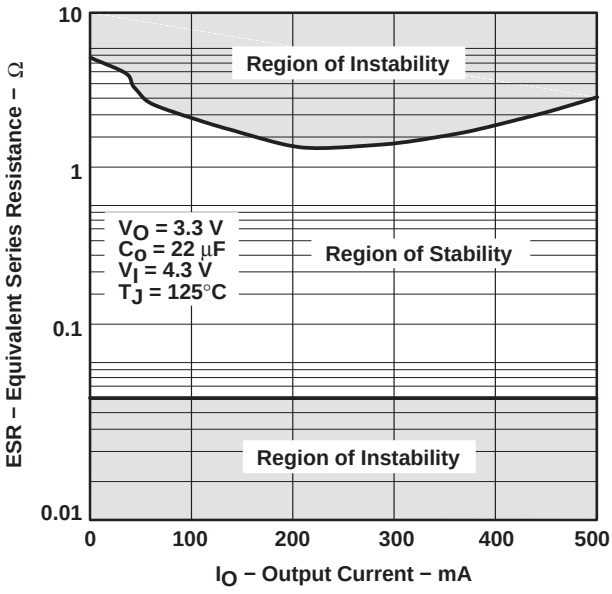


Figure 24

† Equivalent series resistance (ESR) refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to C_O.

APPLICATION INFORMATION

The TPS775xx family includes five fixed-output voltage regulators (1.5 V, 1.6 V, 1.8 V, 2.5 V, and 3.3 V), and an adjustable regulator, the TPS77501 (adjustable from 1.5 V to 5.5 V).

The TPS776xx family includes five fixed-output voltage regulators (1.5 V, 1.8 V, 2.5 V, 2.8 V, and 3.3 V), and an adjustable regulator, the TPS77601 (adjustable from 1.2 V to 5.5 V).

device operation

The TPS775xx and TPS776xx feature very low quiescent current, which remains virtually constant even with varying loads. Conventional LDO regulators use a pnp pass element, the base current of which is directly proportional to the load current through the regulator ($I_B = I_C/\beta$). The TPS775xx and TPS776xx use a PMOS transistor to pass current; because the gate of the PMOS is voltage driven, operating current is low and invariable over the full load range.

Another pitfall associated with the pnp-pass element is its tendency to saturate when the device goes into dropout. The resulting drop in β forces an increase in I_B to maintain the load. During power up, this translates to large start-up currents. Systems with limited supply current may fail to start up. In battery-powered systems, it means rapid battery discharge when the voltage decays below the minimum required for regulation. The TPS775xx and TPS776xx quiescent currents remain low even when the regulator drops out, eliminating both problems.

The TPS775xx and TPS776xx families also feature a shutdown mode that places the output in the high-impedance state (essentially equal to the feedback-divider resistance) and reduces quiescent current to 2 μA. If the shutdown feature is not used, $\overline{\text{EN}}$ should be tied to ground.

minimum load requirements

The TPS775xx and TPS776xx families are stable even at zero load; no minimum load is required for operation.

FB—pin connection (adjustable version only)

The FB pin is an input pin to sense the output voltage and close the loop for the adjustable option . The output voltage is sensed through a resistor divider network to close the loop as it is shown in Figure 26. Normally, this connection should be as short as possible; however, the connection can be made near a critical circuit to improve performance at that point. Internally, FB connects to a high-impedance wide-bandwidth amplifier and noise pickup feeds through to the regulator output. Routing the FB connection to minimize/avoid noise pickup is essential.

external capacitor requirements

An input capacitor is not usually required; however, a ceramic bypass capacitor (0.047 μF or larger) improves load transient response and noise rejection if the TPS775xx or TPS776xx are located more than a few inches from the power supply. A higher-capacitance electrolytic capacitor may be necessary if large (hundreds of milliamps) load transients with fast rise times are anticipated.

Like all low dropout regulators, the TPS775xx and TPS776xx require an output capacitor connected between OUT and GND to stabilize the internal control loop. The minimum recommended capacitance value is 10 μF and the ESR (equivalent series resistance) must be between 50 mΩ and 1.5 Ω. Capacitor values 10 μF or larger are acceptable, provided the ESR is less than 1.5 Ω. Solid tantalum electrolytic, aluminum electrolytic, and multilayer ceramic capacitors are all suitable, provided they meet the requirements described previously.

APPLICATION INFORMATION

external capacitor requirements (continued)

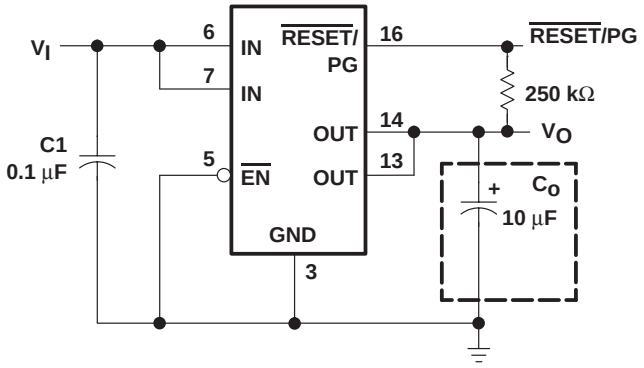


Figure 25. Typical Application Circuit (Fixed Versions)

programming the TPS77x01 adjustable LDO regulator

The output voltage of the TPS77x01 adjustable regulator is programmed using an external resistor divider as shown in Figure 26. The output voltage is calculated using:

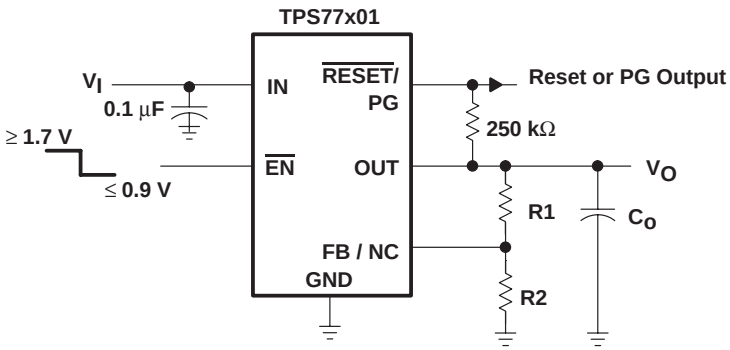
$$V_O = V_{ref} \times \left(1 + \frac{R1}{R2}\right) \quad (1)$$

Where:

V_{ref} = 1.1834 V typ (the internal reference voltage)

Resistors R1 and R2 should be chosen for approximately 10-μA divider current. Lower value resistors can be used but offer no inherent advantage and waste more power. Higher values should be avoided as leakage currents at FB increase the output voltage error. The recommended design procedure is to choose R2 = 110 kΩ to set the divider current at approximately 10 μA and then calculate R1 using:

$$R1 = \left(\frac{V_O}{V_{ref}} - 1\right) \times R2 \quad (2)$$



OUTPUT VOLTAGE PROGRAMMING GUIDE

OUTPUT VOLTAGE	R1	R2	UNIT
2.5 V	121	110	kΩ
3.3 V	196	110	kΩ
3.6 V	226	110	kΩ
4.75 V	332	110	kΩ

Figure 26. TPS77x01 Adjustable LDO Regulator Programming

APPLICATION INFORMATION

reset indicator

The TPS775xx features a $\overline{\text{RESET}}$ output that can be used to monitor the status of the regulator. The internal comparator monitors the output voltage: when the output drops to between 92% and 98% of its nominal regulated value, the $\overline{\text{RESET}}$ output transistor turns on, taking the signal low. The open-drain output requires a pullup resistor. If not used, it can be left floating. $\overline{\text{RESET}}$ can be used to drive power-on reset circuitry or as a low-battery indicator. $\overline{\text{RESET}}$ does not assert itself when the regulated output voltage falls outside the specified 2% tolerance, but instead reports an output voltage low relative to its nominal regulated value (refer to timing diagram for start-up sequence).

power-good indicator

The TPS776xx features a power-good (PG) output that can be used to monitor the status of the regulator. The internal comparator monitors the output voltage: when the output drops to between 92% and 98% of its nominal regulated value, the PG output transistor turns on, taking the signal low. The open-drain output requires a pullup resistor. If not used, it can be left floating. PG can be used to drive power-on reset circuitry or used as a low-battery indicator.

regulator protection

The TPS775xx and TPS776xx PMOS-pass transistors have a built-in back diode that conducts reverse currents when the input voltage drops below the output voltage (e.g., during power down). Current is conducted from the output to the input and is not internally limited. When extended reverse voltage is anticipated, external limiting may be appropriate.

The TPS775xx and TPS776xx also feature internal current limiting and thermal protection. During normal operation, the TPS775xx and TPS776xx limit output current to approximately 1.7 A. When current limiting engages, the output voltage scales back linearly until the overcurrent condition ends. While current limiting is designed to prevent gross device failure, care should be taken not to exceed the power dissipation ratings of the package. If the temperature of the device exceeds 150°C(typ), thermal-protection circuitry shuts it down. Once the device has cooled below 130°C(typ), regulator operation resumes.

APPLICATION INFORMATION

power dissipation and junction temperature

Specified regulator operation is assured to a junction temperature of 125°C; the maximum junction temperature should be restricted to 125°C under normal operating conditions. This restriction limits the power dissipation the regulator can handle in any given application. To ensure the junction temperature is within acceptable limits, calculate the maximum allowable dissipation, $P_{D(max)}$, and the actual dissipation, P_D, which must be less than or equal to $P_{D(max)}$.

The maximum-power-dissipation limit is determined using the following equation:

$$P_{D(max)} = \frac{T_J max - T_A}{R_{\theta JA}}$$

Where:

$T_J max$ is the maximum allowable junction temperature.

$R_{\theta JA}$ is the thermal resistance junction-to-ambient for the package, i.e., 32.6°C/W for the 20-terminal PWP with no airflow.

T_A is the ambient temperature.

The regulator dissipation is calculated using:

$$P_D = \left(V_I - V_O\right) \times I_O$$

Power dissipation resulting from quiescent current is negligible. Excessive power dissipation will trigger the thermal protection circuit.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
TPS77501QPWPRQ1	ACTIVE	HTSSOP	PWP	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
TPS77515QPWPRQ1	ACTIVE	HTSSOP	PWP	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
TPS77518QPWPRQ1	ACTIVE	HTSSOP	PWP	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
TPS77525QPWPRQ1	ACTIVE	HTSSOP	PWP	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
TPS77533QPWPRQ1	ACTIVE	HTSSOP	PWP	20	1	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
TPS77601QPWPRG4Q1	ACTIVE	HTSSOP	PWP	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
TPS77601QPWPRQ1	ACTIVE	HTSSOP	PWP	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
TPS77615QPWPRQ1	ACTIVE	HTSSOP	PWP	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
TPS77618QPWPRQ1	ACTIVE	HTSSOP	PWP	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
TPS77625QPWPRQ1	ACTIVE	HTSSOP	PWP	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
TPS77633QPWPRQ1	ACTIVE	HTSSOP	PWP	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF TPS77501-Q1, TPS77515-Q1, TPS77518-Q1, TPS77525-Q1, TPS77533-Q1, TPS77601-Q1, TPS77615-Q1, TPS77618-Q1, TPS77625-Q1, TPS77633-Q1 :

- Catalog: TPS77501, TPS77515, TPS77518, TPS77525, TPS77533, TPS77601, TPS77615, TPS77618, TPS77625, TPS77633
- Enhanced Product: TPS77501-EP, TPS77515-EP, TPS77518-EP, TPS77525-EP, TPS77533-EP, TPS77601-EP, TPS77615-EP, TPS77618-EP, TPS77625-EP, TPS77633-EP

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TPS77501QPWPRQ1	Active	Production	HTSSOP (PWP) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	77501Q1
TPS77501QPWPRQ1.A	Active	Production	HTSSOP (PWP) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	77501Q1
TPS77533QPWPRQ1	Active	Production	HTSSOP (PWP) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	77533Q1
TPS77533QPWPRQ1.A	Active	Production	HTSSOP (PWP) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	77533Q1
TPS77601QPWPRG4Q1	Active	Production	HTSSOP (PWP) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	77601Q1
TPS77601QPWPRG4Q1.A	Active	Production	HTSSOP (PWP) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	77601Q1
TPS77601QPWPRQ1	Active	Production	HTSSOP (PWP) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	77601Q1
TPS77601QPWPRQ1.A	Active	Production	HTSSOP (PWP) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	77601Q1
TPS77618QPWPRQ1	Active	Production	HTSSOP (PWP) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	77618Q1
TPS77618QPWPRQ1.A	Active	Production	HTSSOP (PWP) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	77618Q1
TPS77633QPWPRQ1	Active	Production	HTSSOP (PWP) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	77633Q1
TPS77633QPWPRQ1.A	Active	Production	HTSSOP (PWP) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	77633Q1

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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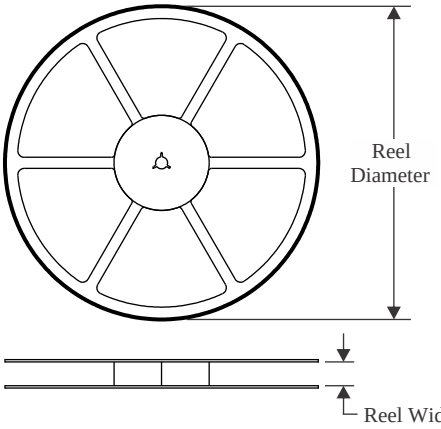
- Catalog : TPS775, TPS776

NOTE: Qualified Version Definitions:

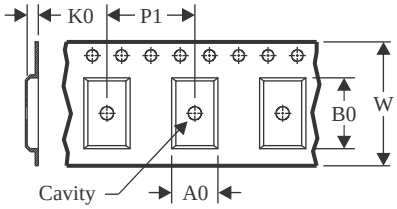
- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION

REEL DIMENSIONS

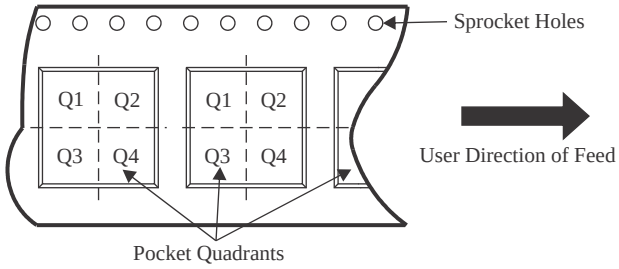


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

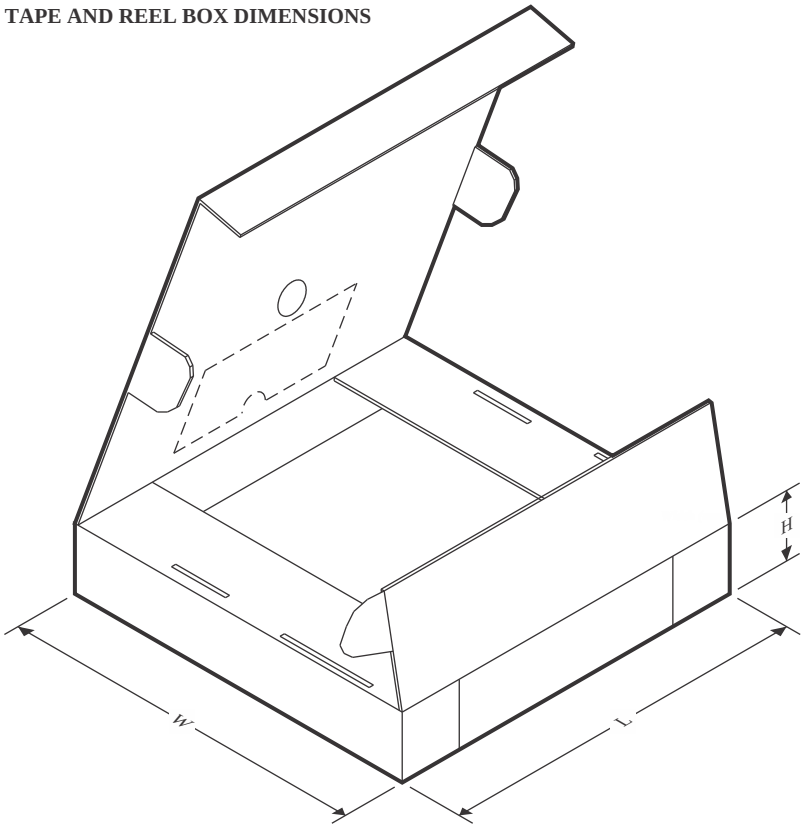
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS77501QPWPRQ1	HTSSOP	PWP	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
TPS77533QPWPRQ1	HTSSOP	PWP	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
TPS77601QPWPRG4Q1	HTSSOP	PWP	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
TPS77601QPWPRQ1	HTSSOP	PWP	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
TPS77618QPWPRQ1	HTSSOP	PWP	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
TPS77633QPWPRQ1	HTSSOP	PWP	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS77501QPWPRQ1	HTSSOP	PWP	20	2000	350.0	350.0	43.0
TPS77533QPWPRQ1	HTSSOP	PWP	20	2000	350.0	350.0	43.0
TPS77601QPWPRG4Q1	HTSSOP	PWP	20	2000	350.0	350.0	43.0
TPS77601QPWPRQ1	HTSSOP	PWP	20	2000	350.0	350.0	43.0
TPS77618QPWPRQ1	HTSSOP	PWP	20	2000	350.0	350.0	43.0
TPS77633QPWPRQ1	HTSSOP	PWP	20	2000	350.0	350.0	43.0

GENERIC PACKAGE VIEW

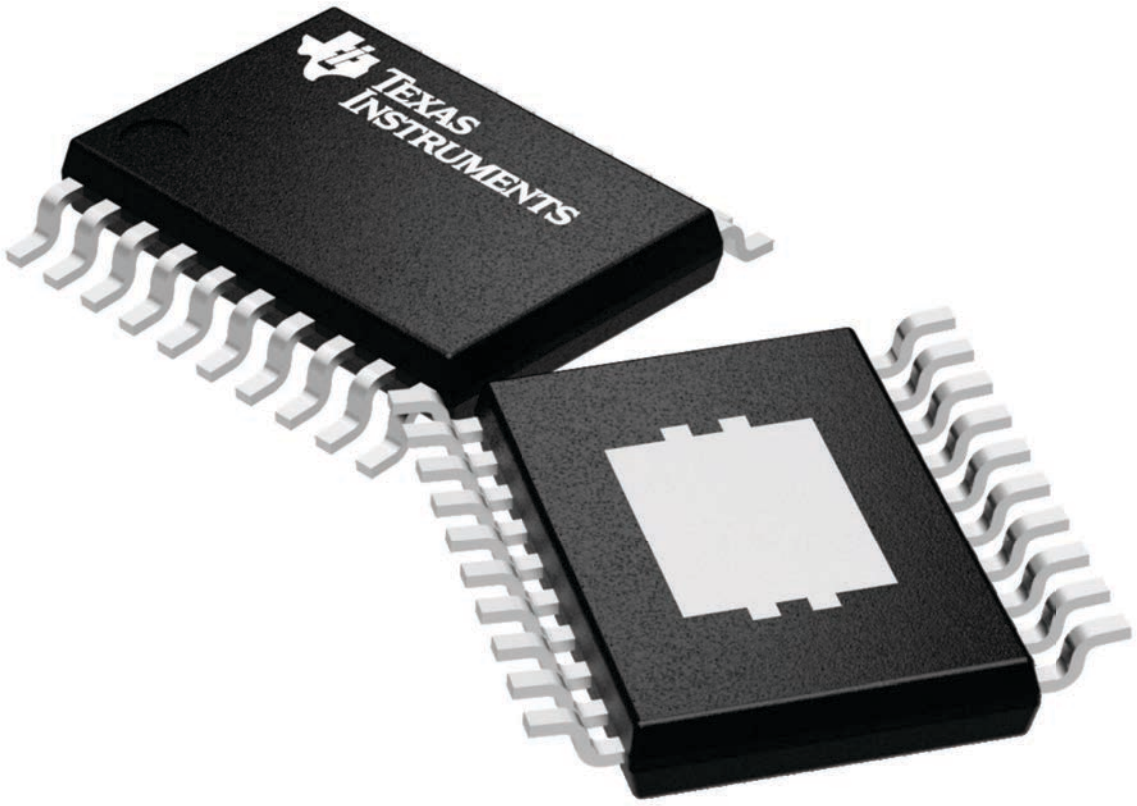
PWP 20

HTSSOP - 1.2 mm max height

6.5 x 4.4, 0.65 mm pitch

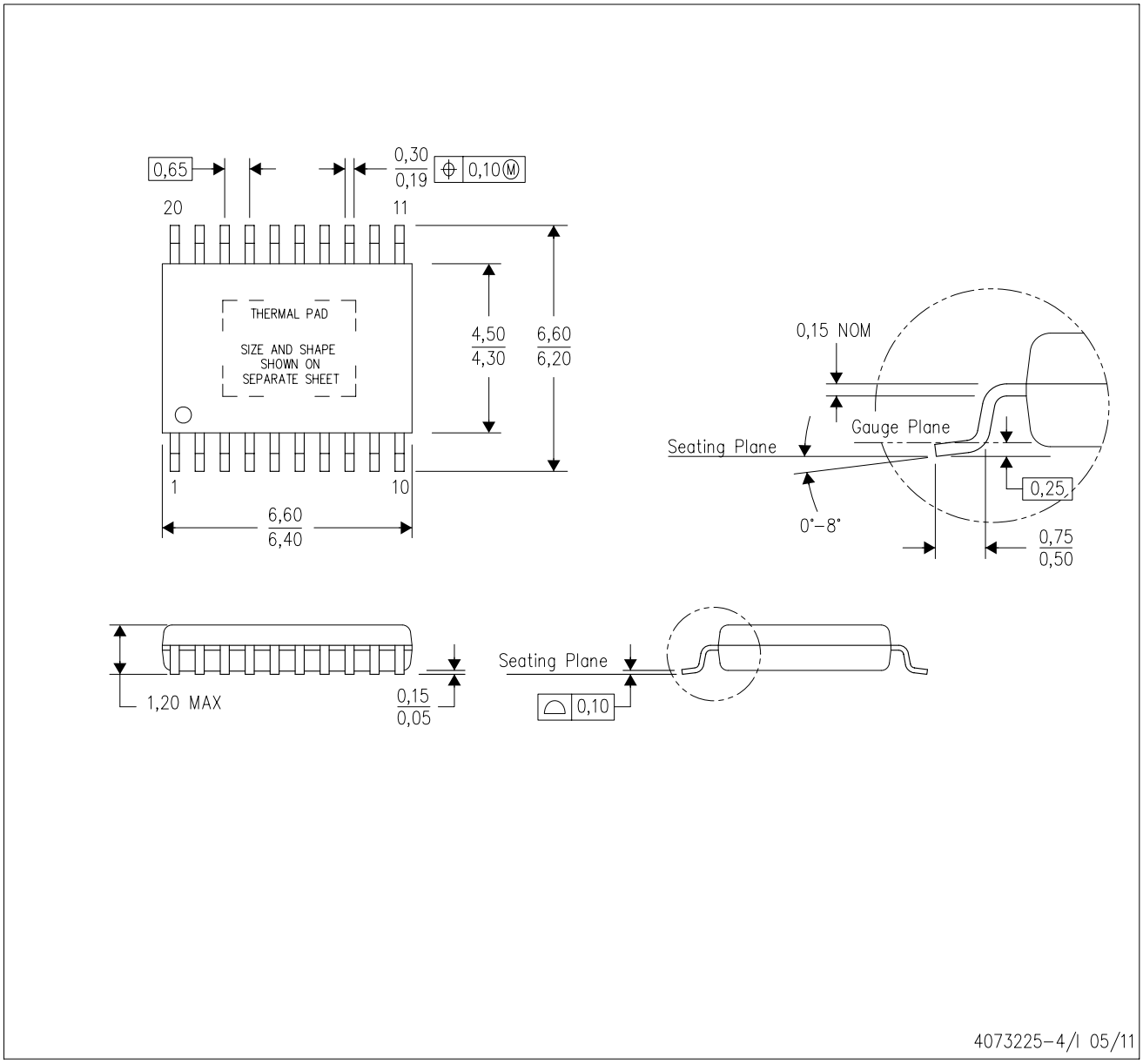
SMALL OUTLINE PACKAGE

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4224669/A

PWP (R–PDSO–G20) PowerPAD™ PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusions. Mold flash and protrusion shall not exceed 0.15 per side.
D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <http://www.ti.com>.
E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
E. Falls within JEDEC MO–153

PowerPAD is a trademark of Texas Instruments.

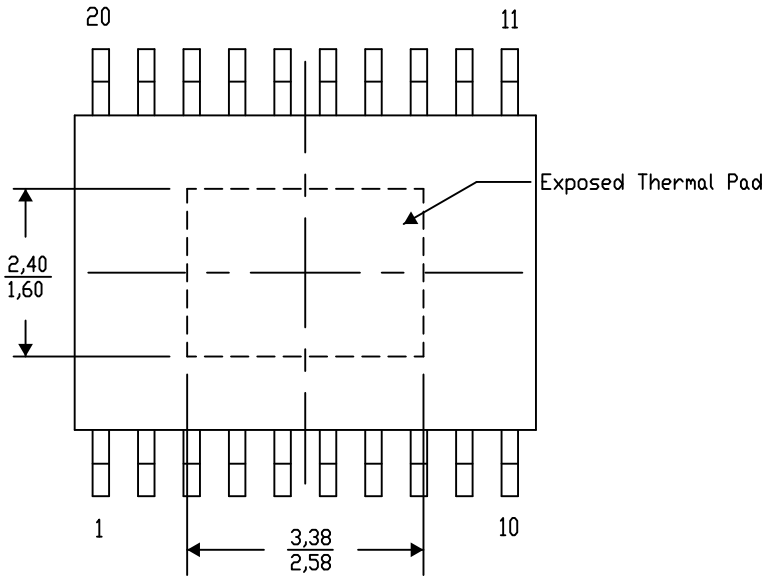
PWP (R–PDSO–G20) PowerPAD™ SMALL PLASTIC OUTLINE

THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Top View

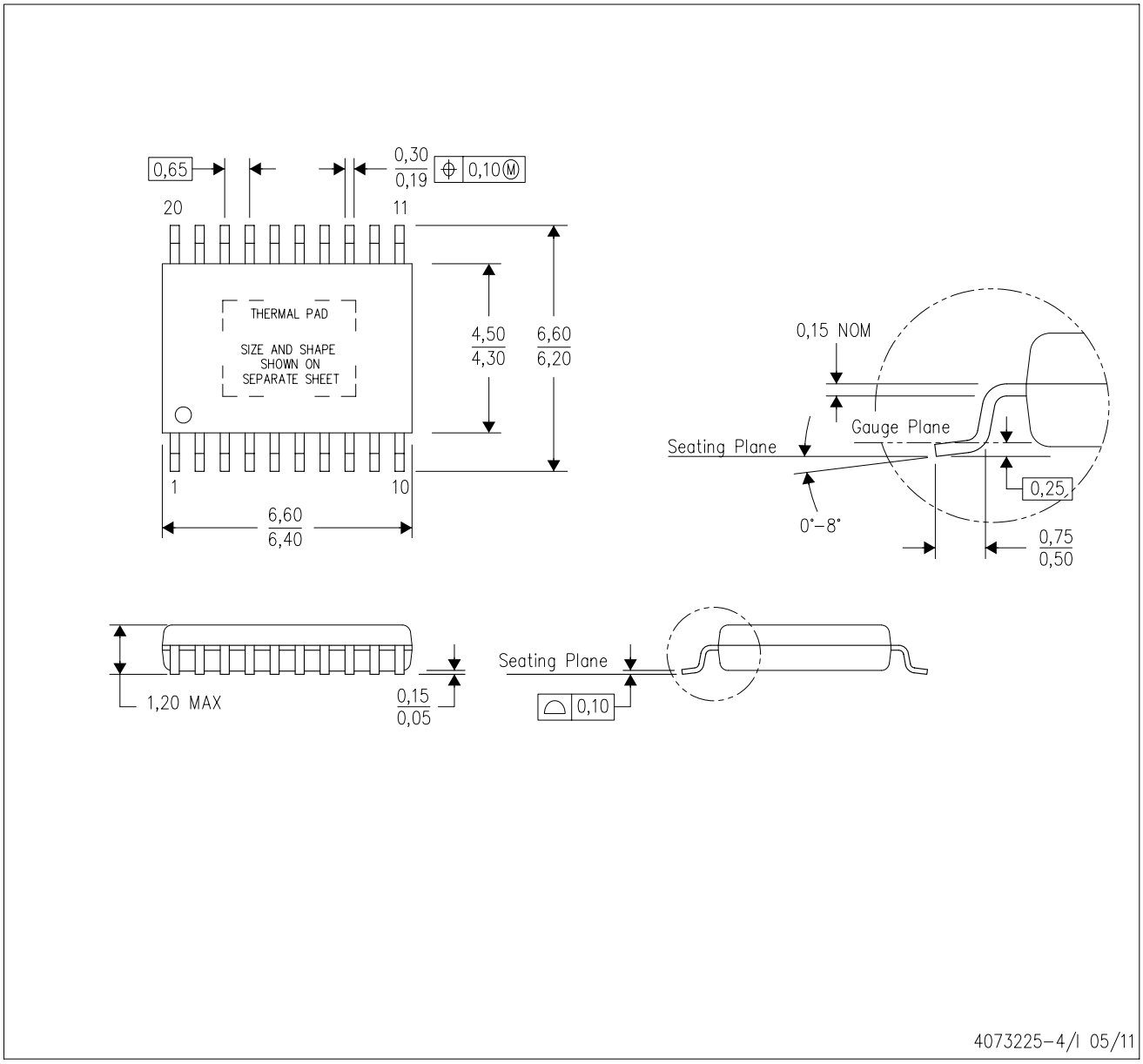
Exposed Thermal Pad Dimensions

4206332–21/AO 01/16

NOTE: A. All linear dimensions are in millimeters

PowerPAD is a trademark of Texas Instruments

PWP (R–PDSO–G20) PowerPAD™ PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusions. Mold flash and protrusion shall not exceed 0.15 per side.
D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <http://www.ti.com>.
E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
E. Falls within JEDEC MO–153

PowerPAD is a trademark of Texas Instruments.

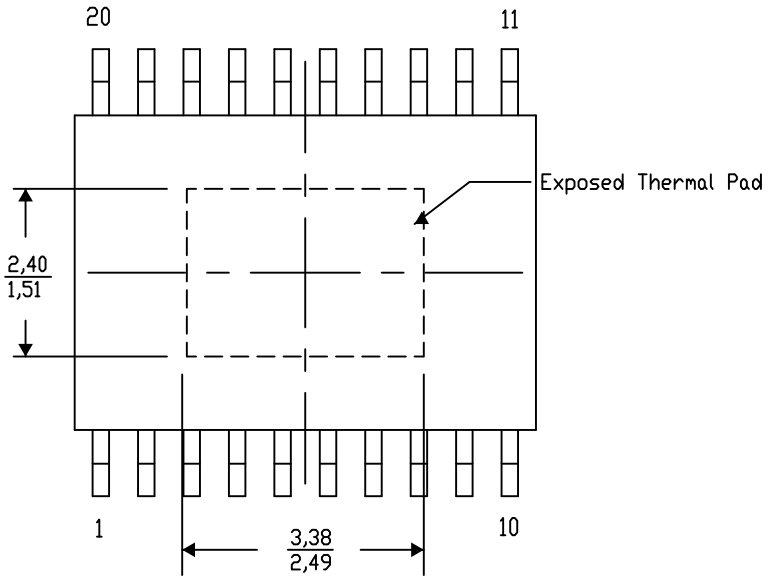
PWP (R–PDSO–G20) PowerPAD™ SMALL PLASTIC OUTLINE

THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

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The exposed thermal pad dimensions for this package are shown in the following illustration.



Top View

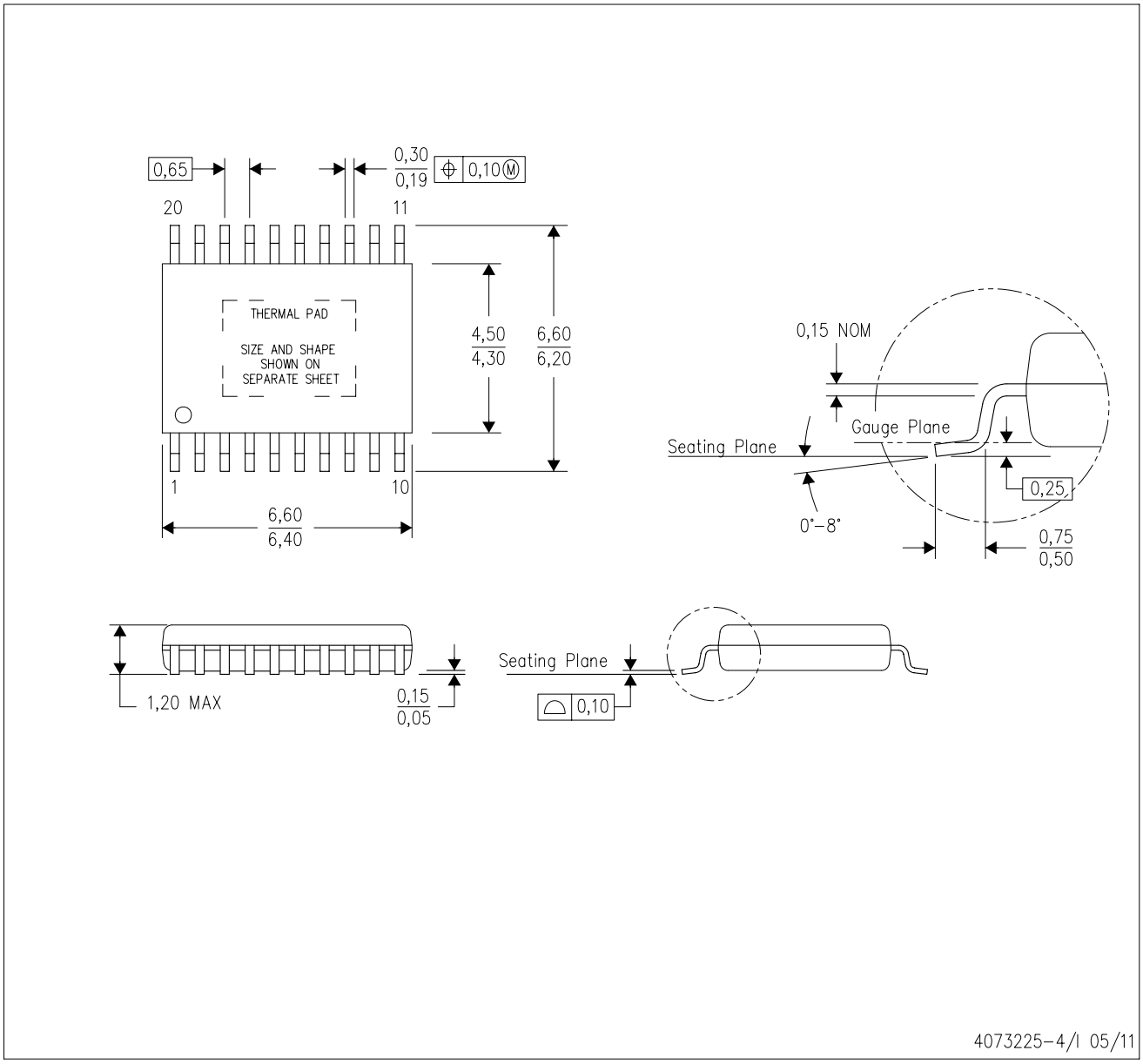
Exposed Thermal Pad Dimensions

4206332–20/AO 01/16

NOTE: A. All linear dimensions are in millimeters

PowerPAD is a trademark of Texas Instruments

PWP (R–PDSO–G20) PowerPAD™ PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusions. Mold flash and protrusion shall not exceed 0.15 per side.
D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <http://www.ti.com>.
E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
E. Falls within JEDEC MO–153

PowerPAD is a trademark of Texas Instruments.

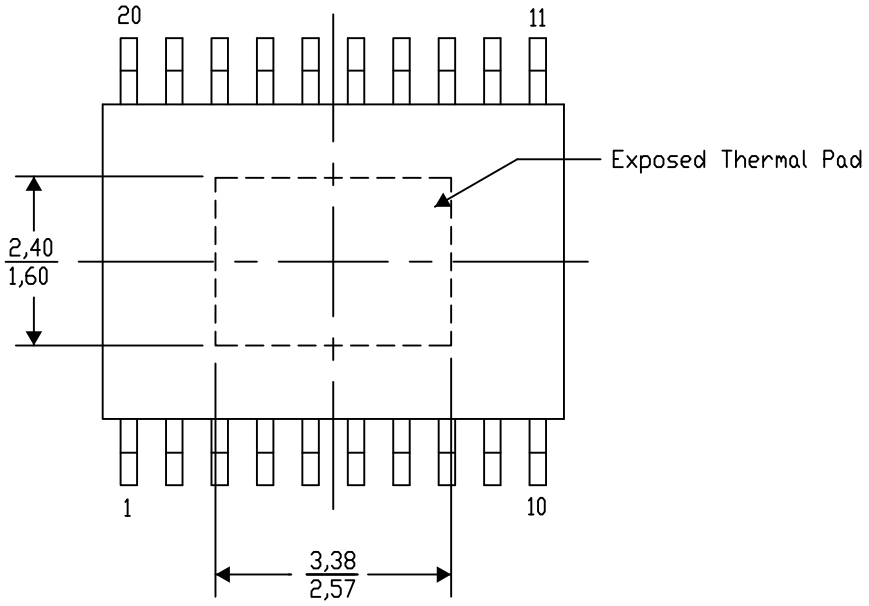
PWP (R–PDSO–G20) PowerPAD™ SMALL PLASTIC OUTLINE

THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

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The exposed thermal pad dimensions for this package are shown in the following illustration.



Top View

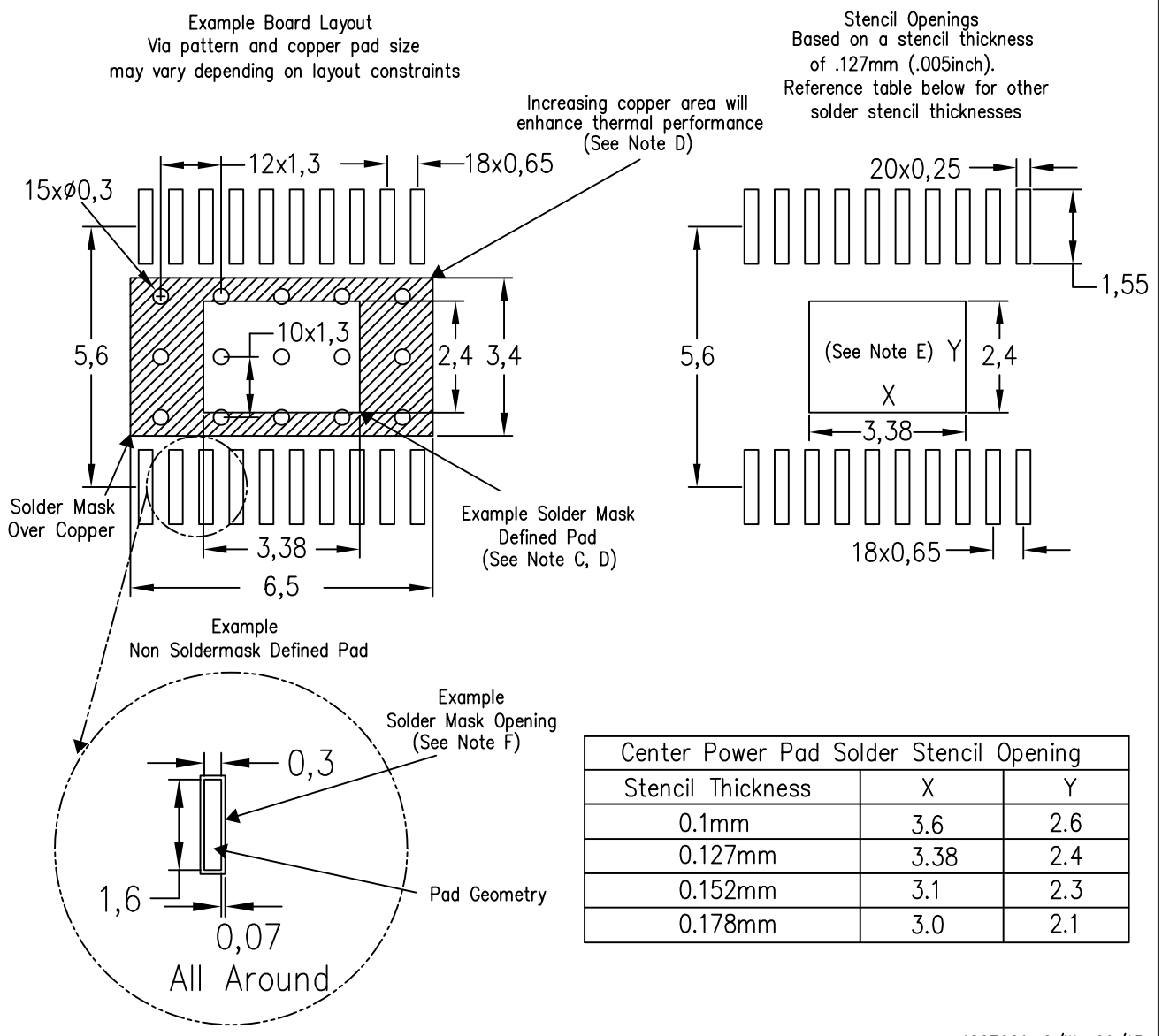
Exposed Thermal Pad Dimensions

4206332–13/AO 01/16

NOTE: A. All linear dimensions are in millimeters

PowerPAD is a trademark of Texas Instruments

PWP (R–PDSO–G20) PowerPAD™ PLASTIC SMALL OUTLINE

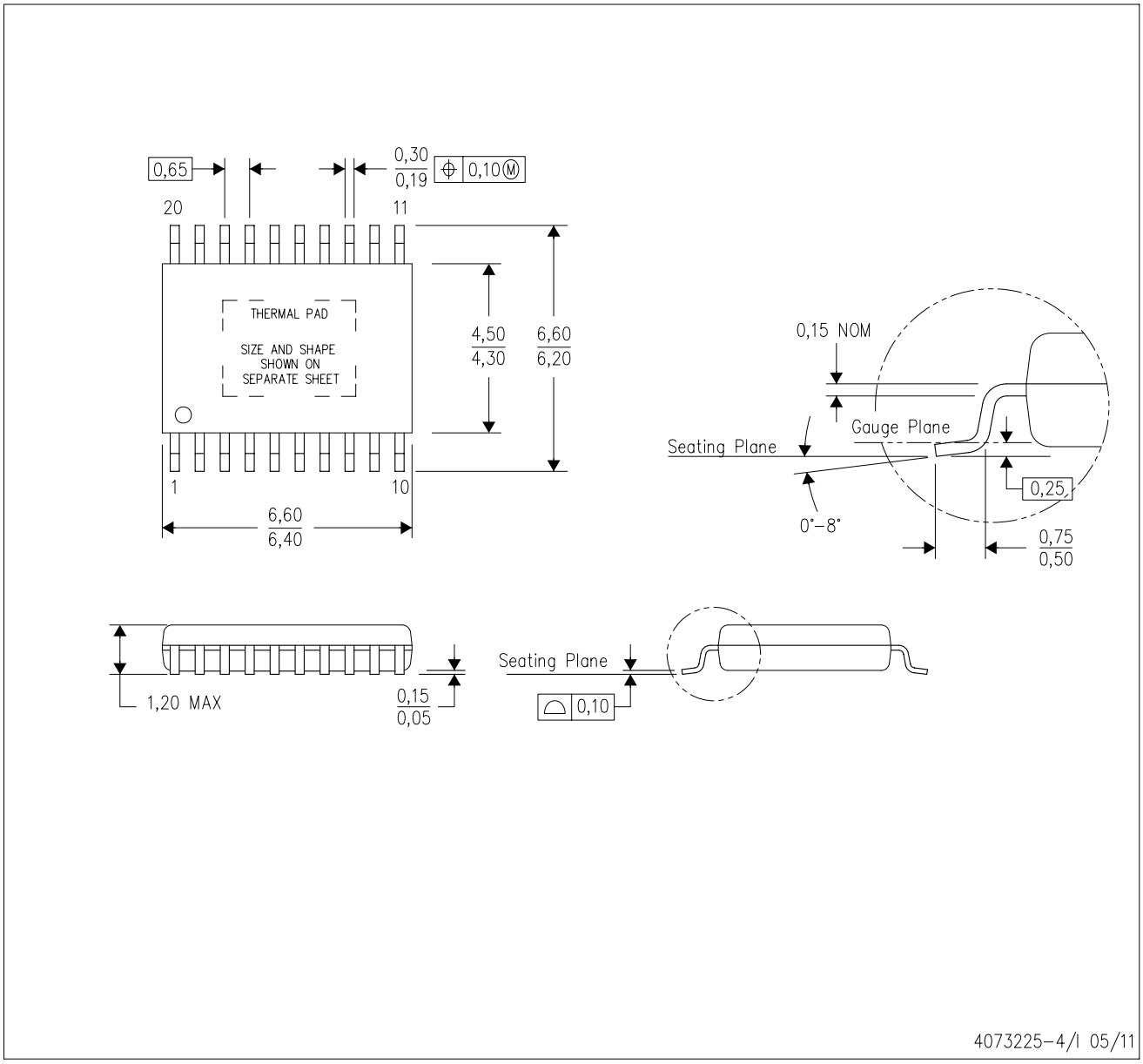


Center Power Pad Solder Stencil Opening		
Stencil Thickness	X	Y
0.1mm	3.6	2.6
0.127mm	3.38	2.4
0.152mm	3.1	2.3
0.178mm	3.0	2.1

4207609–6/W 09/15

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002, SLMA004, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <http://www.ti.com>. Publication IPC–7351 is recommended for alternate designs.
E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC–7525 for other stencil recommendations.
F. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PWP (R–PDSO–G20) PowerPAD™ PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusions. Mold flash and protrusion shall not exceed 0.15 per side.
D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <http://www.ti.com>.
E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
E. Falls within JEDEC MO–153

PowerPAD is a trademark of Texas Instruments.

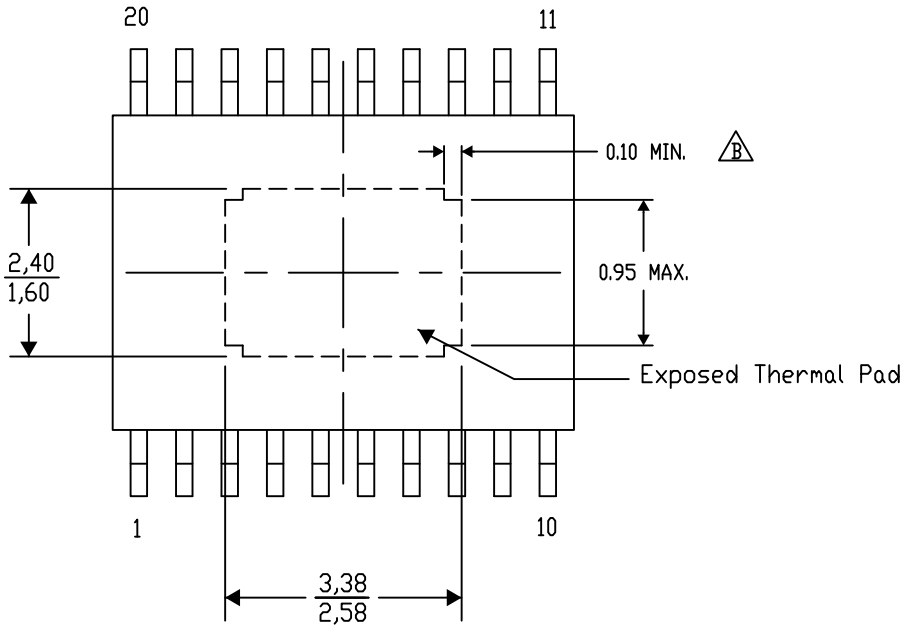
PWP (R–PDSO–G20) PowerPAD™ SMALL PLASTIC OUTLINE

THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

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The exposed thermal pad dimensions for this package are shown in the following illustration.



Top View

Exposed Thermal Pad Dimensions

4206332–23/AO 01/16

NOTE: A. All linear dimensions are in millimeters

B Exposed tie strap features may not be present.

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Last updated 10/2025

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